

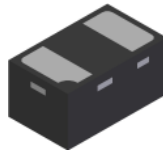
## Features

- Low Profile Package (0.53mm max) and Ultra-Small PCB Footprint Area (1.08 \* 0.68mm max) Suitable for Compact Portable Electronics
- Provides ESD Protection per IEC 61000-4-2 Standard: Air  $\pm 30\text{kV}$ , Contact  $\pm 25\text{kV}$
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

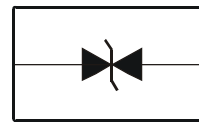
## Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 <sup>(4)</sup>
- Polarity: Cathode Band
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Bottom View



Device Schematic

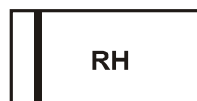
## Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size(inches)	Tape Width(mm)	Quantity per Reel
DESD3V3S1BL-7B	Standard	RH	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information

X1-DFN1006-2



RH = Product Type Marking Code  
Line Denotes Pin#1

**Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	$P_{PP}$	35	W	8/20 $\mu\text{s}$ , Per Figure 3
Peak Pulse Current	$I_{PP}$	5	A	8/20 $\mu\text{s}$ , Per Figure 3
ESD Protection – Contact Discharge	$V_{ESD\_CONTACT}$	$\pm 25$	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	$V_{ESD\_AIR}$	$\pm 30$	kV	IEC 61000-4-2 Standard

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	$P_D$	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	$V_{RWM}$	—	—	3.3	V	—
Channel Leakage Current (Note 6)	$I_{RM}$	—	10	100	nA	$V_{RWM} = 3.3\text{V}$
Clamping Voltage, Positive Transients	$V_{CL}$	—	4.5 5.8	5.4 7.0	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$ $I_{PP} = 5\text{A}, t_p = 8/20\mu\text{s}$
Breakdown Voltage	$V_{BR}$	3.8	—	6.5	V	$I_R = 1\text{mA}$
Differential Resistance	$R_{DIF}$	—	0.3	—	$\Omega$	$I_R = 1\text{A}$
Channel Input Capacitance	$C_T$	—	10	13	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
  6. Short duration pulse test used to minimize self-heating effect.

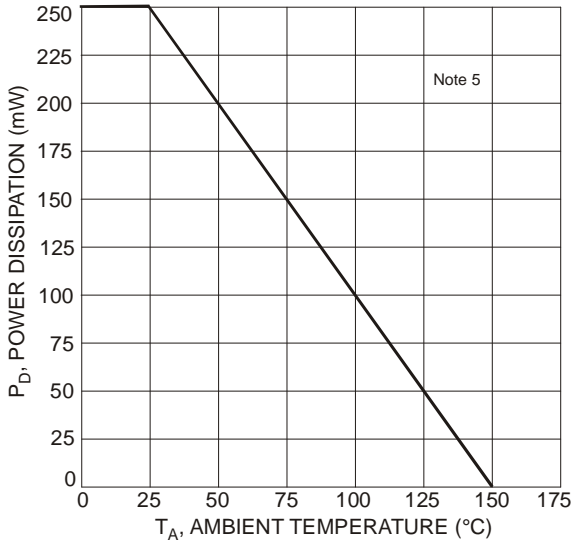


Figure 1 Power Derating Curve

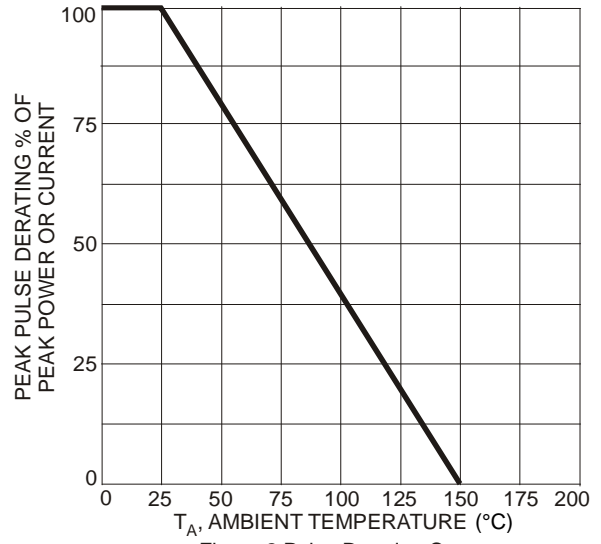


Figure 2 Pulse Derating Curve

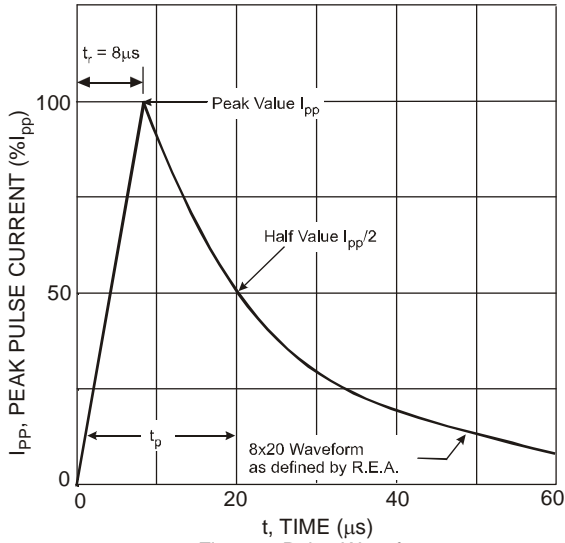


Figure 3 Pulse Waveform

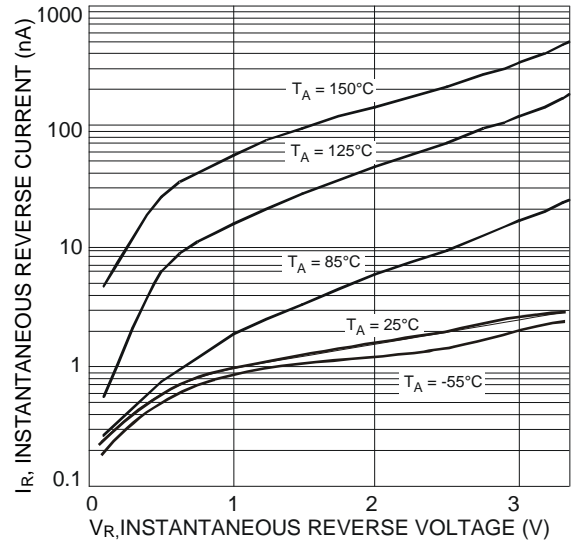


Figure 4 Typical Reverse Characteristics

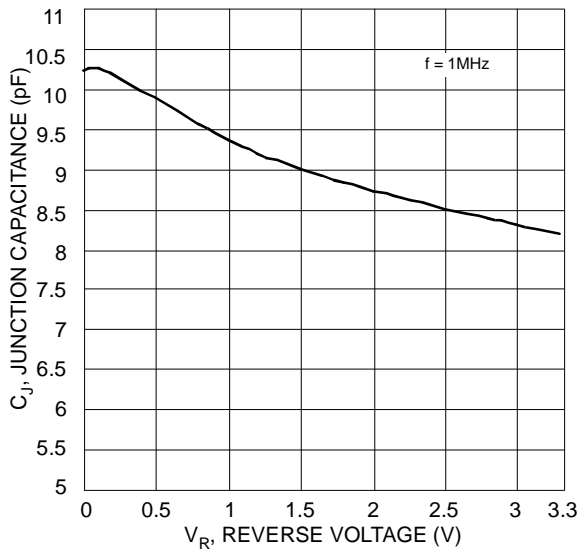


Figure 5 Typical Capacitance

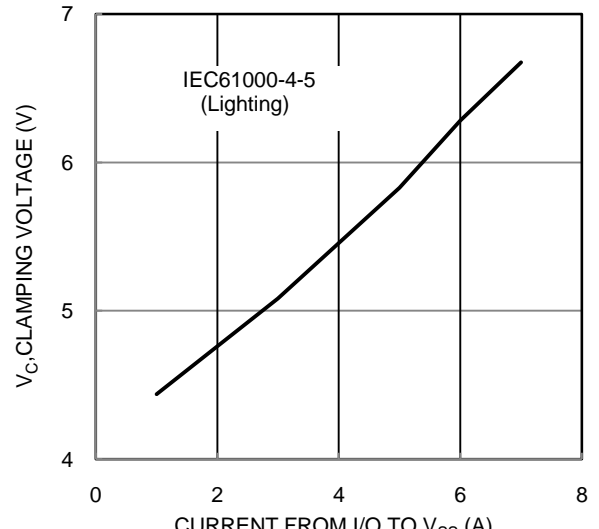
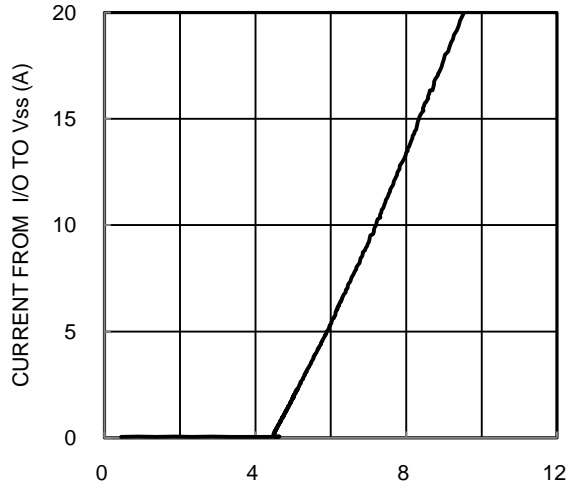


Figure 6 Clamping Voltage Characteristic

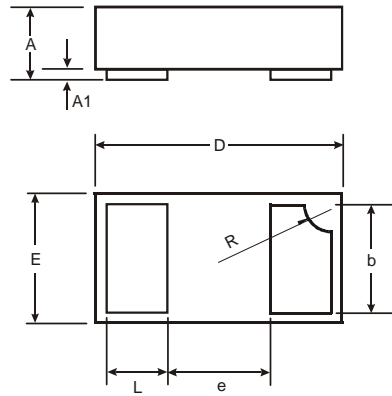


VOLTAGE FROM I/O TO Vss (V)  
Figure 7 Current vs. Voltage

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**

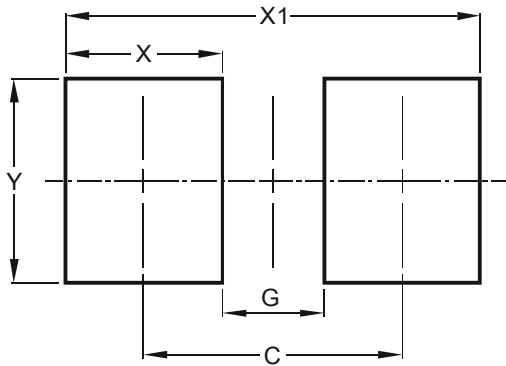


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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